

SOT1653-1

FBGA780, plastic, fine-pitch ball grid array; 780 bumps; 0.8 mm pitch; 23 mm x 23 mm x 2.46 mm body

16 September 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA780
Package type industry code	FBGA780
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-01-2016
Manufacturer package code	98ASA00854D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	23	-	mm
package width	-	23	-	mm
seated height	-	2.46	2.61	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	780	-	



FBGA780, plastic, fine-pitch ball grid array; 780 bumps; 0.8 mm pitch; 23 mm x 23 mm x 2.46 mm body

2 Package outline

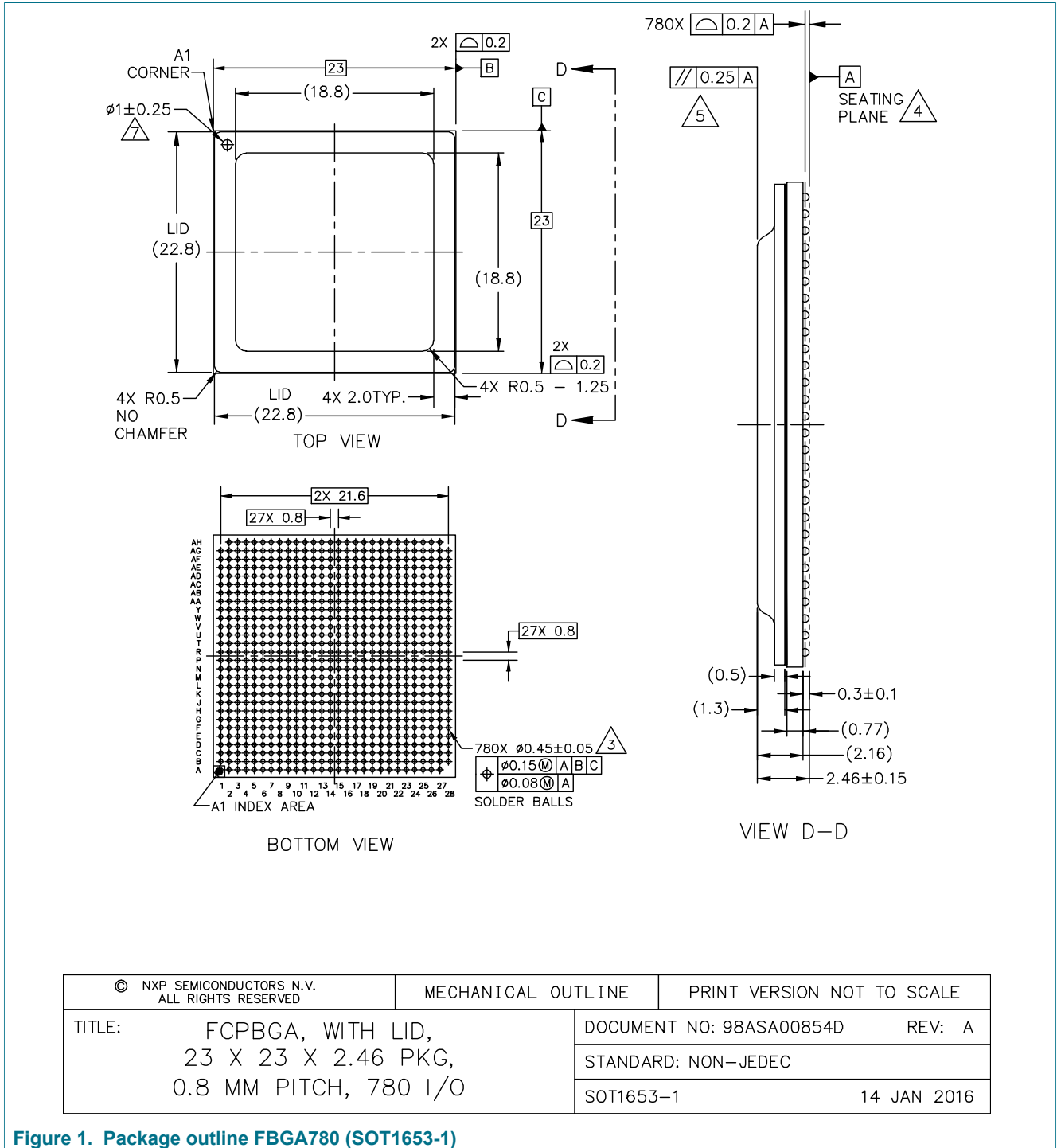


Figure 1. Package outline FBGA780 (SOT1653-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.
7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN FOOT AREA.
8. 23.2MM MAXIMUM PACKAGE ASSEMBLY (LID + LAMINATE) X AND Y.

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TITLE: FCPBGA, WITH LID, 23 X 23 X 2.46 PKG, 0.8 MM PITCH, 780 I/O	DOCUMENT NO: 98ASA00854D		REV: A
	STANDARD: NON-JEDEC		
	SOT1653-1		14 JAN 2016

Figure 2. Package outline note FBGA780 (SOT1653-1)

3 Legal information

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